

## 3.2x2.4mm SMD CHIP LED LAMP

APD3224SYC

SUPER BRIGHT YELLOW

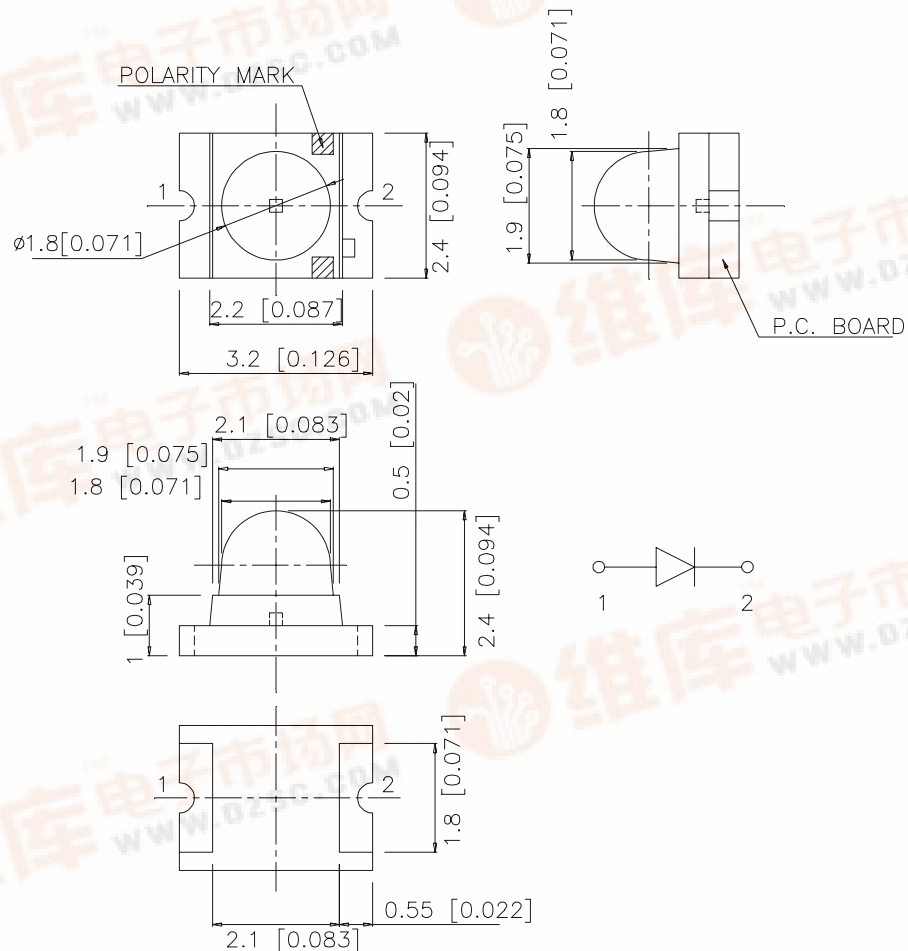
### Features

- 3.2x2.4mm SMT LED, 2.4mm THICKNESS.
- LOW POWER CONSUMPTION.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 1500PCS / REEL.

### Description

The Super Bright Yellow source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

### Package Dimensions



### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.1$  (0.004") unless otherwise noted.
3. Specifications are subject to change without notice.

## Selection Guide

Part No.	Dice	Lens Type	I <sub>v</sub> (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	θ1/2
APD3224SYC	SUPER BRIGHT YELLOW (InGaAlP)	WATER CLEAR	180	700	20°

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

## Electrical / Optical Characteristics at T<sub>A</sub>=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ <sub>peak</sub>	Peak Wavelength	Super Bright Yellow	590		nm	I <sub>F</sub> =20mA
λ <sub>D</sub>	Dominate Wavelength	Super Bright Yellow	588		nm	I <sub>F</sub> =20mA
Δλ1/2	Spectral Line Half-width	Super Bright Yellow	28		nm	I <sub>F</sub> =20mA
C	Capacitance	Super Bright Yellow	25		pF	V <sub>F</sub> =0V;f=1MHz
V <sub>F</sub>	Forward Voltage	Super Bright Yellow	2.0	2.5	V	I <sub>F</sub> =20mA
I <sub>R</sub>	Reverse Current	Super Bright Yellow		10	μA	V <sub>R</sub> = 5V

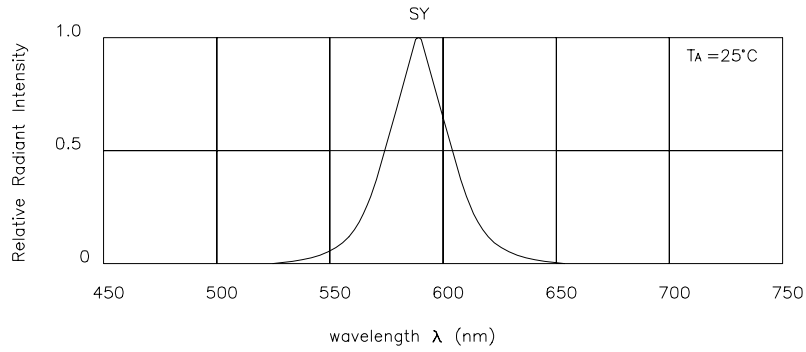
## Absolute Maximum Ratings at T<sub>A</sub>=25°C

Parameter	Super Bright Yellow	Units
Power dissipation	125	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

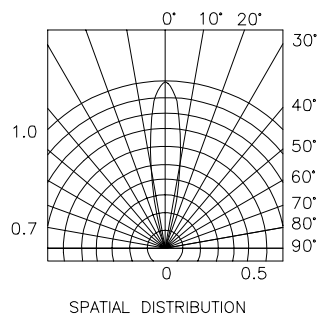
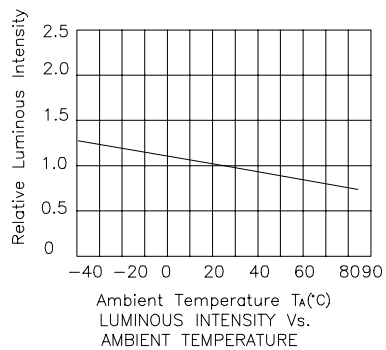
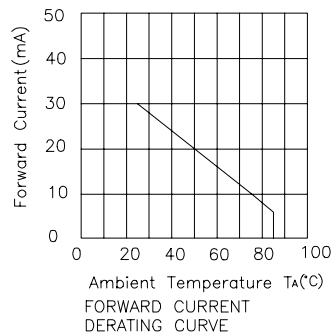
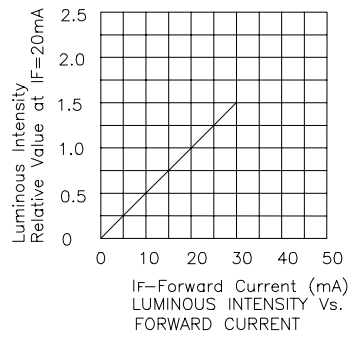
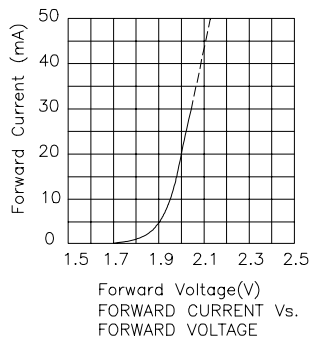
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

# Kingbright



## Super Bright Yellow APD3224SYC

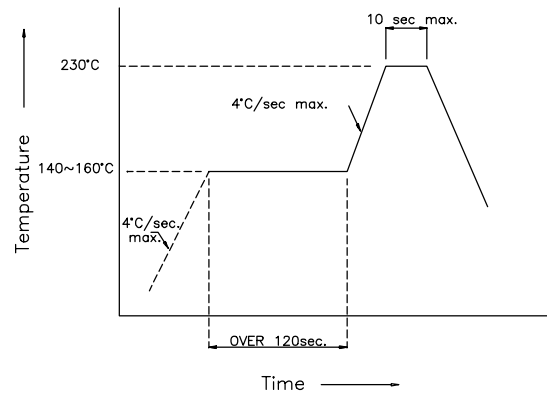


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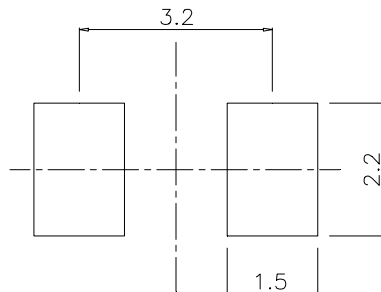
## APD3224SYC

### SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



### Recommended Soldering Pattern (Units : mm)



### Tape Specifications (Units : mm)

